



**Declaration of RoHS compliance  
(2011/65/EU and all subsequent amendments to date)**

We hereby confirm and assure that

<input checked="" type="checkbox"/>	The product family, specified in the annex	D3222
<input type="checkbox"/>	The specific product range	
<input type="checkbox"/>	The products listed in the annex	

is/are compliant with Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (recast) and all subsequent amendments to date.

We hereby declare that in the product(s) named above

no legal exemption is used and that the products specified above do not contain hazardous substances exceeding the threshold limits of RoHS.

the following exemptions are used

6(a)	6(b)	6(c)	7(a)	7(c)-I											
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Additional exemptions,  
not listed above

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Adress

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Applications exempted from the restriction in Directive 2011/65/EU, Article 4(1)  
Excerpt, relevant for IT equipment

3(a)	Mercury in cold cathode fluorescent lamps and external electrode fluorescent lamps (CCFL and EEFL) for special purposes not exceeding (per lamp): - Short length ( ≤ 500 mm): 3,5 mg may be used per lamp
3(b)	Mercury in cold cathode fluorescent lamps and external electrode fluorescent lamps (CCFL and EEFL) for special purposes not exceeding (per lamp): - Medium length ( > 500 mm and ≤ 1500 mm): 5 mg may be used per lamp
3(c)	Mercury in cold cathode fluorescent lamps and external electrode fluorescent lamps (CCFL and EEFL) for special purposes not exceeding (per lamp): - Long length ( > 1,500 mm): 13 mg may be used per lamp
5(a)	Lead in glass of cathode ray tubes
5(b)	Lead in glass of fluorescent tubes not exceeding 0,2 % by weight
6(a)	Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35 % lead by weight
6(b)	Lead as an alloying element in aluminium containing up to 0,4 % lead by weight
6(c)	Copper alloy containing up to 4 % lead by weight
7(a)	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)
7(b)	Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission, and network management for telecommunications
7(c)-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
7(c)-II	Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher
7(c)-IV	Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors
8(b)	Cadmium and its compounds in electrical contacts
9(b)	Lead in bearing shells and bushes for refrigerant-containing compressors for heating, ventilation, air conditioning and refrigeration (HVACR) applications
13(a)	Lead in white glasses used for optical applications
13(b)	Cadmium and lead in filter glasses and glasses used for reflectance standards
15	Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

Rev. of template document:

- 1.0 Initial
- 2.0 Update: Change of format of page "Annex". Adopt to automatic extraction of exemptions  
Update: Add document name in footer. Change date format from automatically set to
- 2.1 manual
- 2.2 Change of signatroy W. Degle -> S. Hornung.